

Product Change Notification / JAON-27UMCB395

Date:

09-Jan-2023

Product Category:

SAS Silicon & SW

PCN Type:

Manufacturing Change

Notification Subject:

CCB 5171 Final Notice: Qualification of HANK as an additional assembly site and WINS as an additional bumping site for selected PM8076B1-F3EI, PM8074B1-F3EI, PM8073B1-F3EI, PM8070B1-F3EI, PM8063B1-F3EI, and PM8006B1-F3EI catalog part numbers (CPN) available in 1071L FBGA (27x27x2.17mm) package.

Affected CPNs:

JAON-27UMCB395_Affected_CPN_01092023.pdf JAON-27UMCB395_Affected_CPN_01092023.csv

Notification Text:

PCN Status: Final Notification

PCN Type:Manufacturing Change

Microchip Parts Affected:Please open one of the files found in the Affected CPNs section. Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

Description of Change:Qualification of HANK as an additional assembly site and WINS as an additional bumping site for selected PM8076B1-F3EI, PM8074B1-F3EI, PM8073B1-F3EI, PM8072B1-F3EI, PM8070B1-F3EI, PM8063B1-F3EI, and PM8006B1-F3EI catalog part numbers (CPN) available in 1071L FBGA (27x27x2.17mm) package.

Pre and Post Change Summary:

	Pre Change	Post Change						
Assembly Site	ASE Inc. (ASE)	ASE Inc. (ASE)	Hana Micron Inc. (HANK)					
Bumping Site	ASE Inc. (ASE)	ASE Inc. (ASE)	Winstek Semiconductor Technology Co.,Ltd. (WINS)					
Substrate core material	E700GR	E700GR	E705G					
SM material	AUS703-140PS	AUS703-140PS	SR7300GR					
Bump material	Sn1.8Ag	Sn1.8Ag	Sn1.8Ag					
Die Attach epoxy	WF6317	WF6317	WF6317					
Underfill material	UA28	UA28	U8410-302LF1					
Solder Ball material	SAC305	SAC305	SAC305					
Solder Ball Flux	WF6317	WF6317	WF6317					

Impacts to Data Sheet:None

Change ImpactNone

Reason for Change:To improve productivity and on-time delivery performance by qualifying HANK as an additional assembly site and WINS as an additional bumping site.

Change Implementation Status: In Progress

Estimated First Ship Date: February 15, 2023 (date code: 2307)

Note: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Time Table Summary:

	July 2022					January 2023			February 2023						
Workweek	2 8	2 9	3 0	3 1	3 2	>	1	2	3	4	5	6	7	8	9
Initial PCN Issue Date			х												
Qual Report Availability								х							
Final PCN Issue Date								Х							

Method to Identify Change: Traceability code

Qualification Report:Please open the attachments included with this PCN labeled as PCN_#_Qual_Report.

Revision History: July 20, 2022: Issued initial notification. January 9, 2023: Issued final notification. Attached the Qualification Report. Provided estimated first ship date to be on February 15, 2023.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachments:

PCN JAON-27UMCB395 Qual Report.pdf

Please contact your local Microchip sales office with questions or concerns regarding this notification.

Terms and Conditions:

If you wish to <u>receive Microchip PCNs via email</u> please register for our PCN email service at our PCN home page select register then fill in the required fields. You will find instructions about registering for Microchips PCN email service in the PCN FAQ section.

If you wish to <u>change your PCN profile, including opt out</u>, please go to the <u>PCN home page</u> select login and sign into your myMicrochip account. Select a profile option from the left navigation bar and make the applicable selections. JAON-27UMCB395 - CCB 5171 Final Notice: Qualification of HANK as an additional assembly site and WINS as an additional bumping site for selected PM8076B1-F3EI, PM8074B1-F3EI, PM8073B1-F3EI, PM8072B1-F3EI, PM8071B1-F3EI, PM8070B1-F3EI, PM8063B1-F3EI, and PM8006B1-F3EI catalog part numbers (CPN) available in 1071L FBGA (27x27x2.17mm) package.

Affected Catalog Part Numbers (CPN)

PM8006B1-F3EI PM8076B1-F3EI PM8074B1-F3EI PM8073B1-F3EI PM8072B1-F3EI PM8071B1-F3EI PM8070B1-F3EI PM8063B1-F3EI